



## Final Product Change Notification

201509015F01

**Issue Date:** 02-Oct-2015  
**Effective Date:** 18-Jan-2016

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# QUALITY

### Management Summary

Release of SO24 with reduced diepad at APB.

#### Change Category

<input type="checkbox"/> Wafer Fab process	<input checked="" type="checkbox"/> Assembly Process	<input type="checkbox"/> Product Marking	<input type="checkbox"/> Design
<input type="checkbox"/> Wafer Fab materials	<input type="checkbox"/> Assembly Materials	<input type="checkbox"/> Electrical spec./Test coverage	<input type="checkbox"/> Mechanical Specification
<input type="checkbox"/> Wafer Fab location	<input type="checkbox"/> Assembly Location	<input type="checkbox"/> Test Location	<input type="checkbox"/> Packing/Shipping/Labeling

SO24 with reduced diepad at APB

### Details of this Change

For manufacturing improvement the diepad size will be reduced from 4.2x5.2mm (rectangular) to 3.2 x 2 plus 4 x 2.8mm (non rectangular).

Based on this improvement action, die-attach and wire bonding (in APB), have been re-assessed and optimized.

The BOM (Bill Of Material) used, i.e. molding compound, lead frame material and plating materials will not be changed.

#### Why do we Implement this Change

Manufactureability improvements.

#### Identification of Affected Products

Product identification does not change

### Product Availability

#### Sample Information

Samples are available upon request

#### Production

Planned first shipment 07-Jan-2016

#### Impact

no impact to the product's functionality anticipated.

#### Data Sheet Revision

No impact to existing datasheet

#### Disposition of Old Products

Existing inventory will be shipped until depleted

#### Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 31-Oct-2015.

## Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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